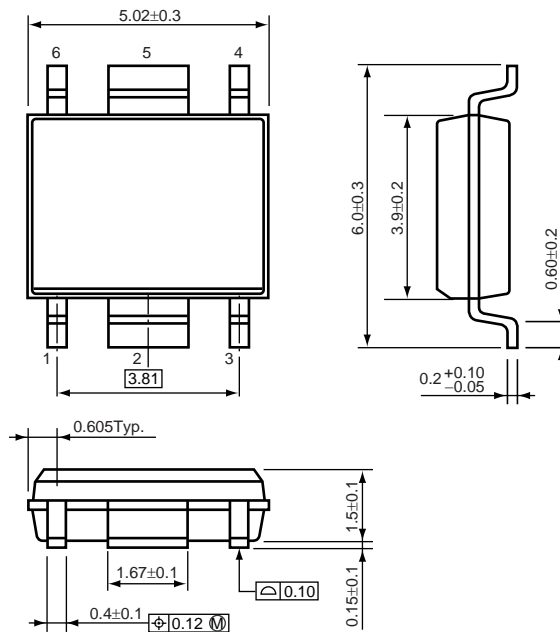


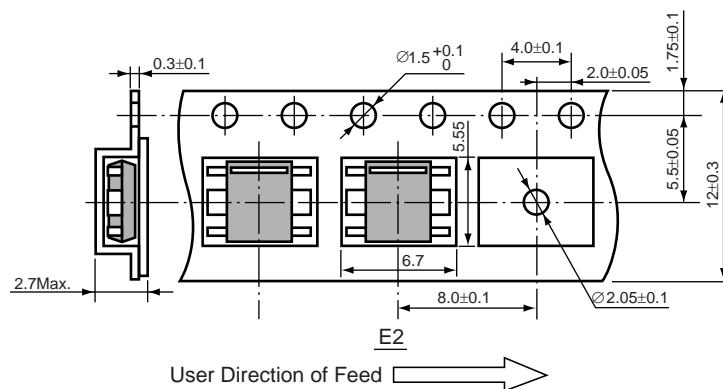
• HSOP-6J

Unit: mm

PACKAGE DIMENSIONS

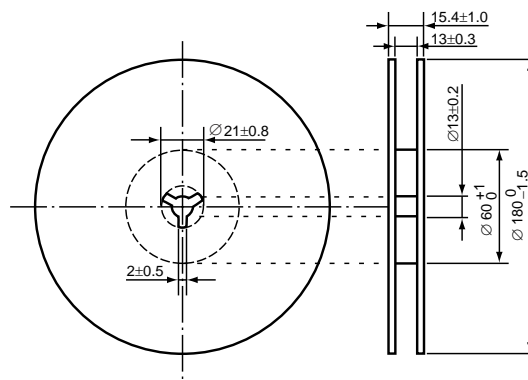


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-12Bc)

(1reel=1,000pcs)



POWER DISSIPATION (HSOP-6J)

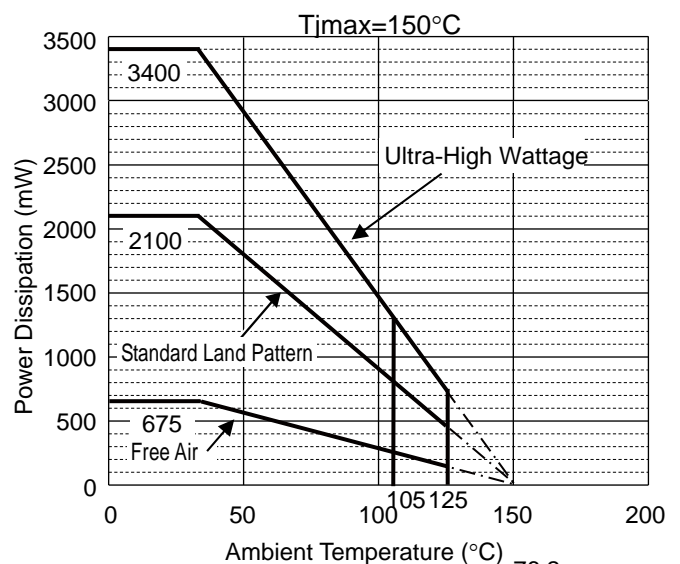
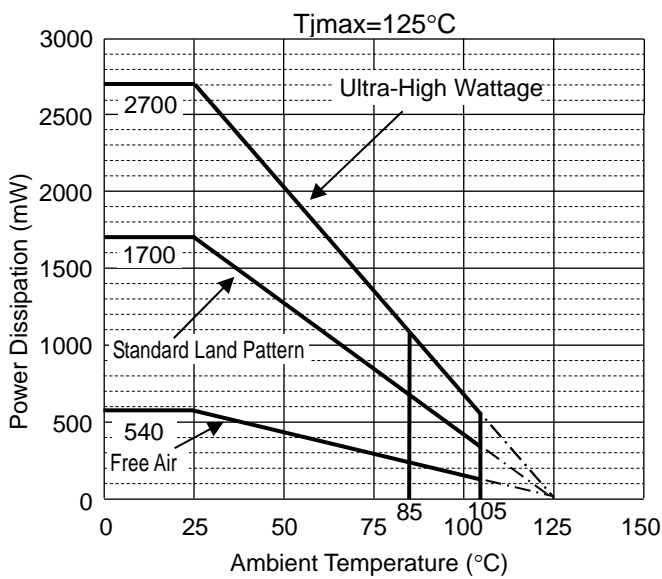
This specification is at mounted on board. Power Dissipation (P_b) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

Measurement Conditions

	Standard Land Pattern	Ultra-High Wattage Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)	Glass cloth epoxy plastic (4 Layers)
Board Dimensions	50 mm × 50 mm × 1.6 mm	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	50%	96%
Through-holes	φ0.5 mm × 24 pcs	φ0.3 mm × 28 pcs

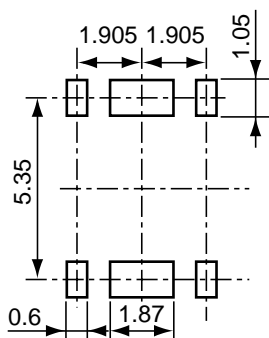
Measurement Results ($T_a = 25^\circ\text{C}$)

	Free Air	Standard Land Pattern	Ultra High Wattage Land Pattern
Power Dissipation	540 mW ($T_{j\text{max}} = 125^\circ\text{C}$) 675 mW ($T_{j\text{max}} = 150^\circ\text{C}$)	1700 mW ($T_{j\text{max}} = 125^\circ\text{C}$) 2100 mW ($T_{j\text{max}} = 150^\circ\text{C}$)	2700 mW ($T_{j\text{max}} = 125^\circ\text{C}$) 3400 mW ($T_{j\text{max}} = 150^\circ\text{C}$)
Thermal Resistance	$\theta_{ja} = 185^\circ\text{C/W}$ $\theta_{jc} = 17.5^\circ\text{C/W}$	$\theta_{ja} = 59^\circ\text{C/W}$	$\theta_{ja} = 37^\circ\text{C/W}$

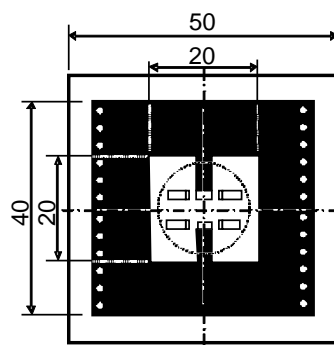


Power Dissipation vs. Ambient Temperature

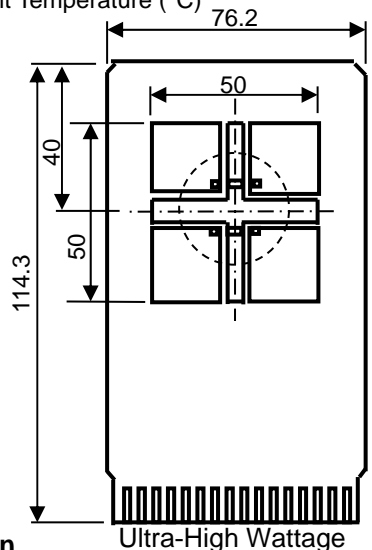
RECOMMENDED LAND PATTERN



(Unit: mm)



Standard
IC Mount Area (Unit: mm)
Measurement Board Pattern



Ultra-High Wattage